

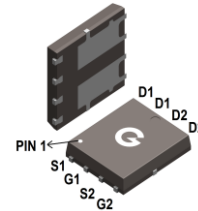
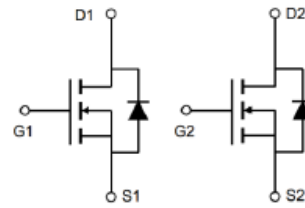
### Features

- Super low gate charge
- Green device available
- Excellent  $C_{dv} / d_t$  effect decline
- Advanced high cell density trench technology

HF

### Mechanical Data

- Case: PDFN5x6-8LC
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



PDFN5x6-8LC

## Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
GBLN6602-5DL8	PDFN5x6-8LC	5000 pcs / Tape & Reel	GBLN6602

## Maximum Ratings (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	60	V
Gate-to-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current ( $T_C = 25^\circ\text{C}$ )	$I_D$	60	A
Continuous Drain Current ( $T_C = 100^\circ\text{C}$ )		40	A
Pulsed Drain Current <sup>*2</sup>	$I_{DM}$	100	A
Single Pulse Avalanche Energy <sup>*3</sup>	$E_{AS}$	73	mJ

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	50	W
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	2.5	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Air <sup>*1</sup>	$R_{\theta JA}$	45	$^\circ\text{C/W}$
Operating Junction & Storage Temperature Range	$T_J, T_{STG}$	-55 ~ +175	$^\circ\text{C}$

### Electrical Characteristics (@ T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
V <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V, T <sub>C</sub> = 25°C	-	-	1	μA
		V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V, T <sub>C</sub> = 55°C	-	-	5	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
<b>On Characteristics</b>						
R <sub>DS(ON)</sub>	Static Drain-Source On-resistance <sup>*2</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 15A	-	10	12	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A	-	13	15	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	1.8	2.5	V
<b>Dynamic Characteristics</b>						
C <sub>ISS</sub>	Input Capacitance	V <sub>GS</sub> = 0V V <sub>DS</sub> = 15V f = 1.0MHz	-	3101	-	pF
C <sub>OSS</sub>	Output Capacitance					
C <sub>RSS</sub>	Reverse Transfer Capacitance					
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> = 30V V <sub>GS</sub> = 10V R <sub>G</sub> = 3.3Ω I <sub>D</sub> = 15A	-	10.6	-	ns
t <sub>r</sub>	Turn-on Rise Time					
t <sub>d(OFF)</sub>	Turn-Off Delay Time					
t <sub>f</sub>	Turn-Off Fall Time					
Q <sub>G</sub>	Total Gate-Charge	V <sub>DD</sub> = 48V V <sub>GS</sub> = 4.5V I <sub>D</sub> = 15A	-	33	-	nC
Q <sub>GS</sub>	Gate to Source Charge					
Q <sub>GD</sub>	Gate to Drain (Miller) Charge					
<b>Source-Drain Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage <sup>*2</sup>	I <sub>SD</sub> = 5A, V <sub>GS</sub> = 0V, T <sub>J</sub> = 25°C	-	0.8	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>F</sub> = 15A, V <sub>R</sub> = 30V di/dt = 100A/μs	-	35	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	34	-	nC

Notes:

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper
- The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
- The E<sub>AS</sub> data shows Max. rating. The test condition is V<sub>DD</sub> = 25V, V<sub>GS</sub> = 10V, L = 0.1mH

Ratings and Characteristics Curves (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

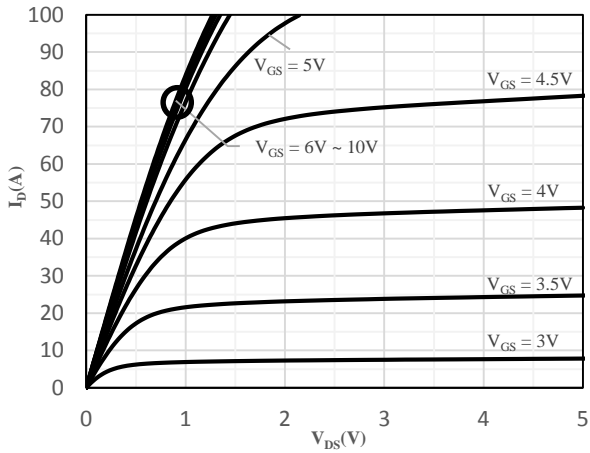


Fig 1 Typical Output Characteristics

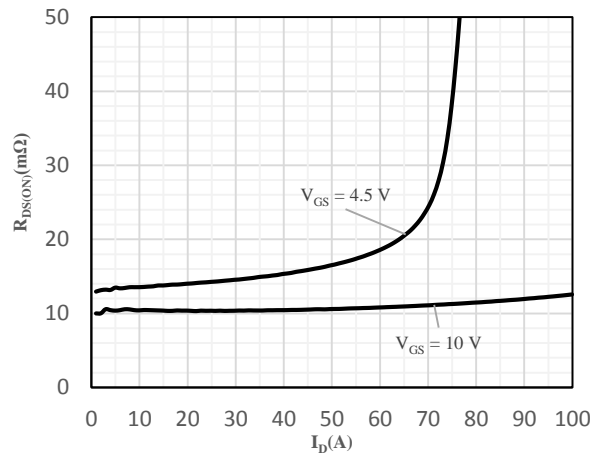


Fig 2 On-Resistance vs. Drain Current and Gate Voltage

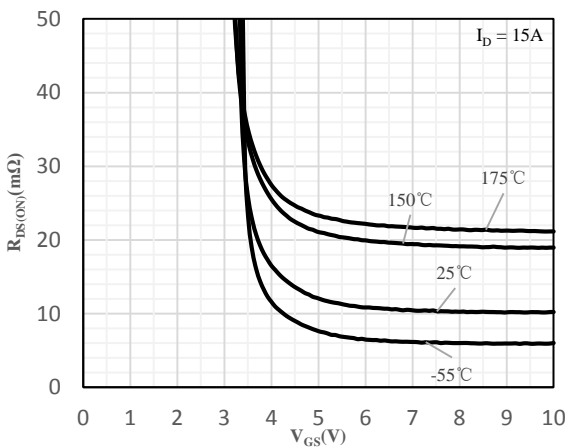


Fig 3 On-Resistance vs. Gate-Source Voltage

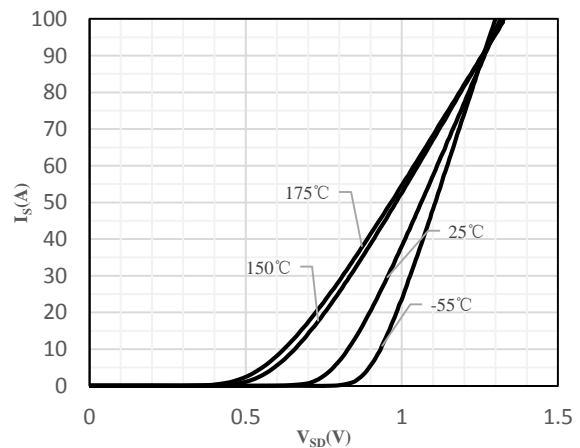


Fig 4 Body-Diode Characteristics

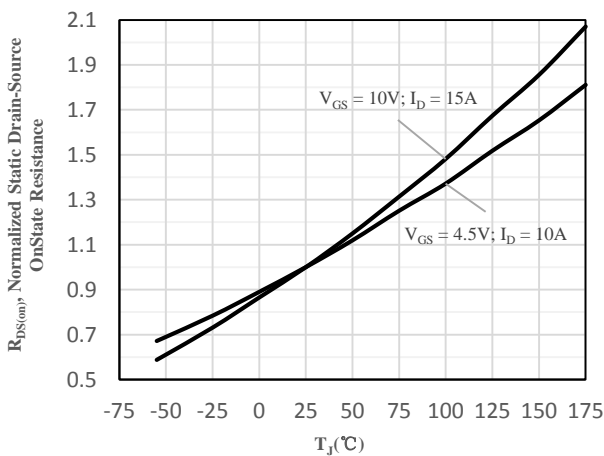


Fig 5 Normalized On-Resistance vs. Junction Temperature

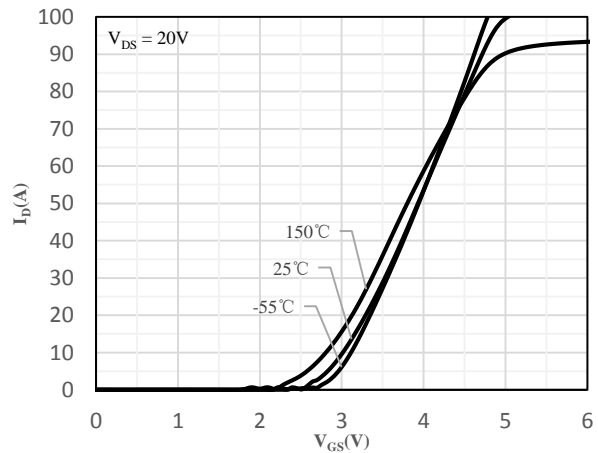


Fig 6 Transfer Characteristics

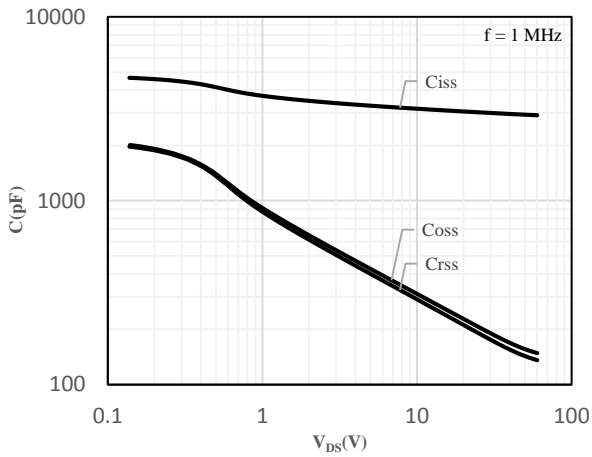


Fig 7 Capacitance Characteristics

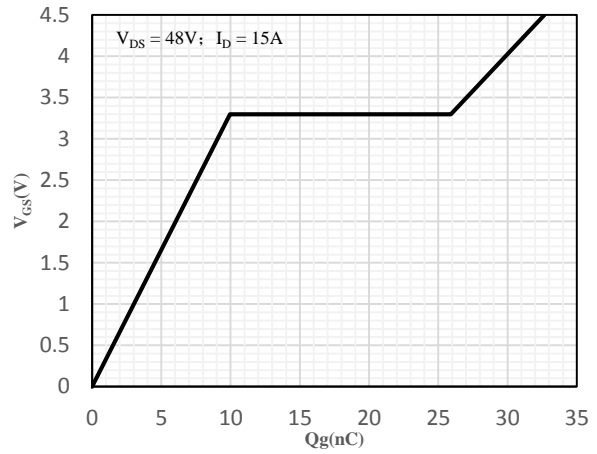


Fig 8 Gate-Charge Characteristics

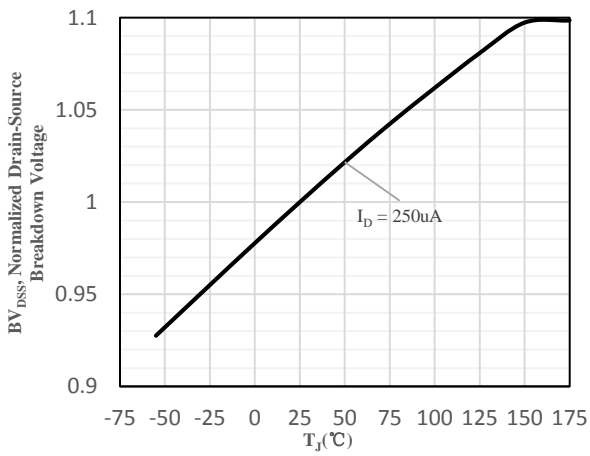


Fig 9 Normalized Breakdown Voltage  
vs. Junction Temperature

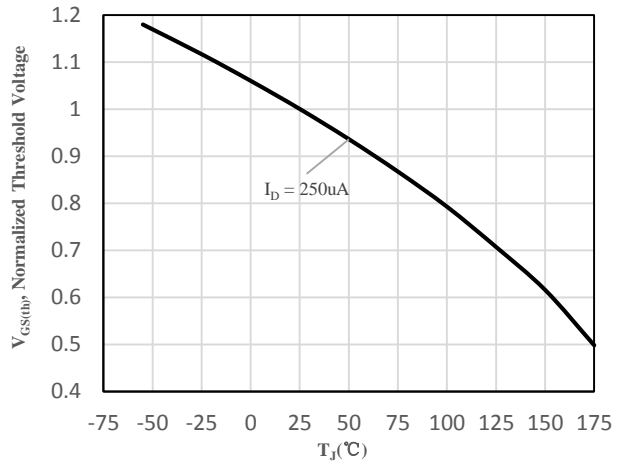


Fig 10 Normalized  $V_{GS(th)}$  vs. Junction Temperature

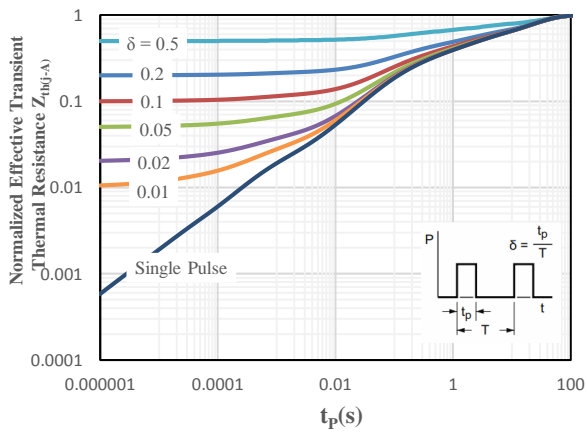
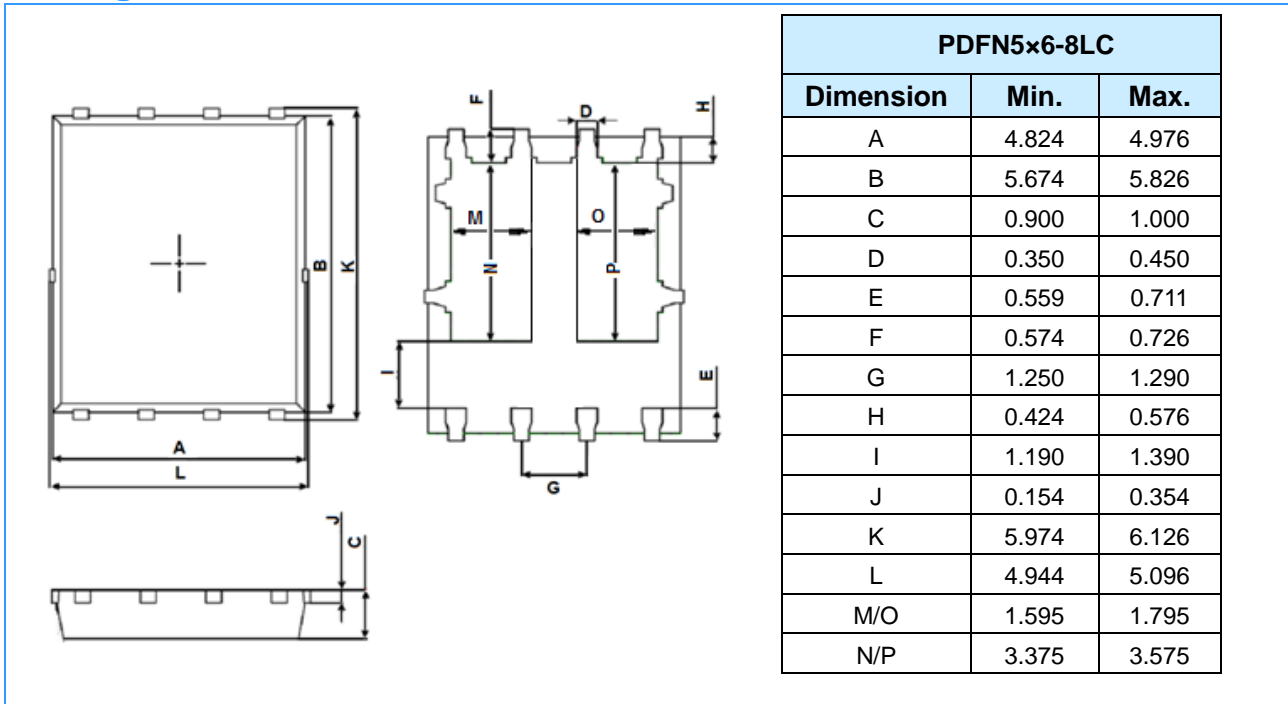
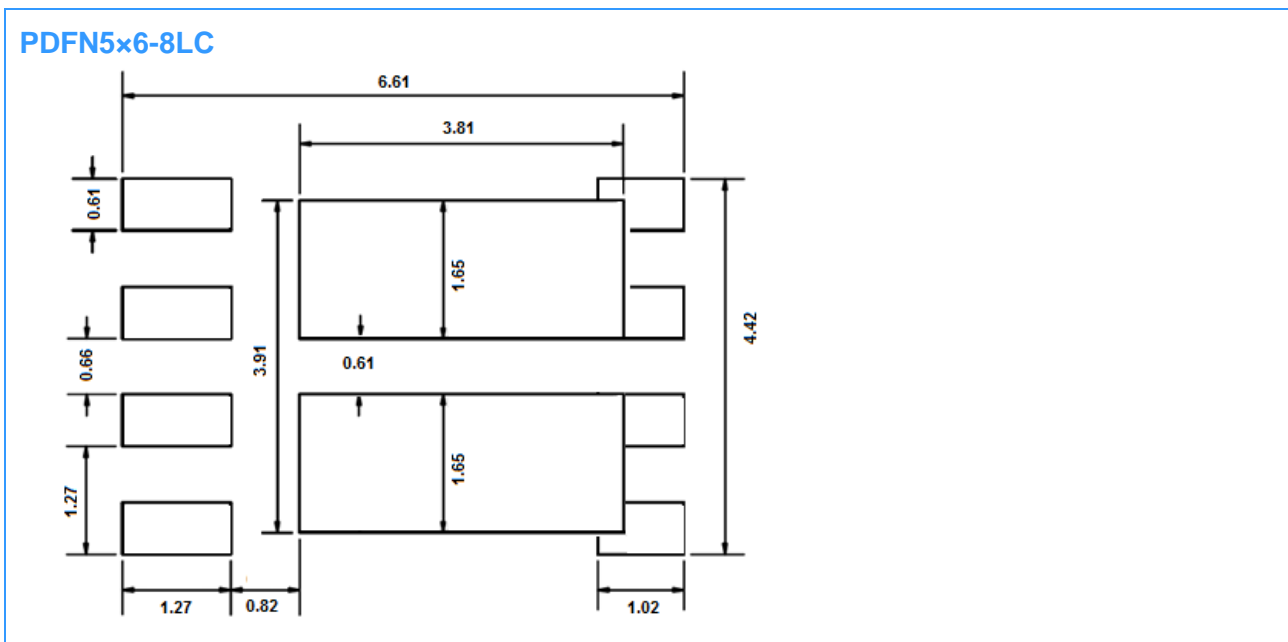


Fig 11 Normalized Maximum transient thermal  
impedance

### Package Outline Dimensions (Unit: mm)



### Mounting Pad Layout (Unit: mm)



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